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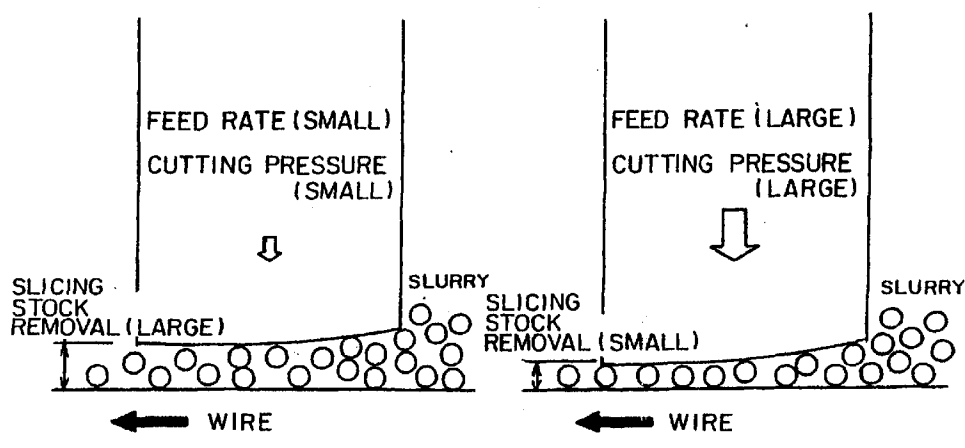
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(54) **Method of slicing a workpiece through use of a wire saw, and a wire saw**

(57) There is disclosed a method of slicing a workpiece through use of a wire saw. The workpiece is pressed at a predetermined feed rate against a wire which moves from a wire feed side to a wire take-up side and slices the workpiece into wafers while abrasive grain slurry is fed to the press contact portion between the wire and the workpiece. The feed rate of the work-

piece is controlled according to the size of abrasive grains in the abrasive grain slurry, such that a decrease in the slicing stock removal stemming from a decrease in the size of abrasive grains during slicing is compensated with an increase in the slicing stock removal effected by decreasing the feed rate of the workpiece. The method can make the thicknesses of sliced wafers uniform to the extent possible.

FIG. 3

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EUROPEAN SEARCH REPORT

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DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.Cl.6)
A	US 3 831 576 A (H. MECH) 27 August 1974 * column 2, line 58 - column 3, line 6 * * column 4, line 29 - line 41 * * column 5, line 61 - column 6, line 10; figure 1 *	1, 5	B28D5/04
T	----- PATENT ABSTRACTS OF JAPAN vol. 098, no. 002, 30 January 1998 -& JP 09 262826 A (SHIN ETSU HANDOTAI CO LTD), 7 October 1997 * abstract * -----	1	
			TECHNICAL FIELDS SEARCHED (Int.Cl.6)
			B23D B28D
The present search report has been drawn up for all claims			
Place of search THE HAGUE		Date of completion of the search 17 September 1998	Examiner Moet, H
CATEGORY OF CITED DOCUMENTS X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document			

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